

### 插件磁珠

Ferrite Bead (Sleeve Choke)



#### 特性

Characteristics

易于PCB组装的铁氧体磁芯

Ferrite cores for easy PCB assembly

额定电流: 3 A

Rated current: 3 A

工作温度: -25°C至+125°C

Operating temperature: -25 °C to +125 °C

#### 应用

Application

THT组件

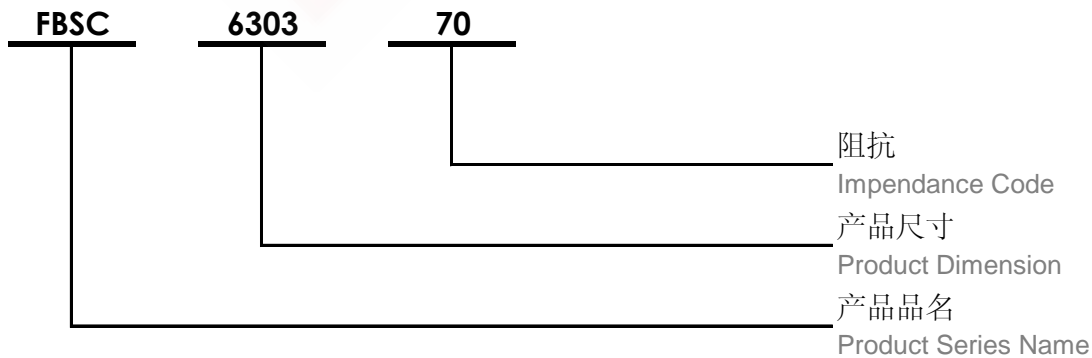
THT components

传感器

Sensors

#### 产品品名介绍

Product Number Structure





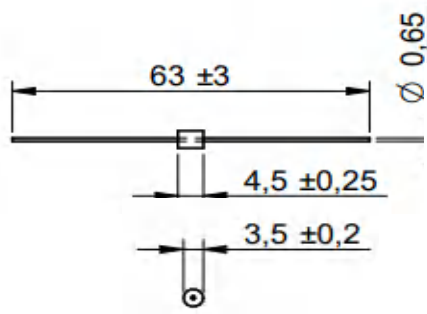
### 尺寸

Dimension (mm)



### 示意图

Schematics



### 电性特性

Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I <sub>R</sub> 40°C max (A)	直流电阻 DCResistance DCRmax (mΩ)	电感 Inductance L <sub>p</sub> typ (μH)	固化温度 Curie Temperature T <sub>c</sub> °C
FBSC6303-70	@10MHz 28 @100MHz 70	3.00	5.00	0.360	140



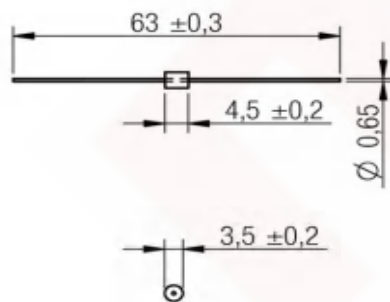
### 尺寸

Dimension (mm)



### 示意图

Schematics



### 电性特性

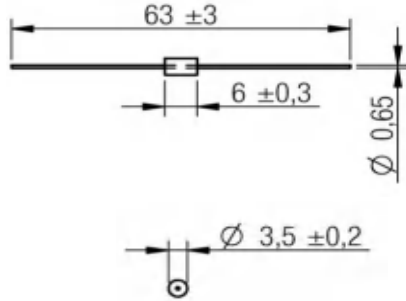
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I <sub>R</sub> 40°C max (A)	直流电阻 DCResistance DCRmax (mΩ)	电感 Inductance L <sub>p</sub> typ (μH)	固化温度 Curie Temperature T <sub>c</sub> °C
FBSC6303-80	@10MHz 20 @100MHz 80	3.00	5.00	0.360	140



### 尺寸

Dimension (mm)



### 示意图

Schematics



### 电性特性

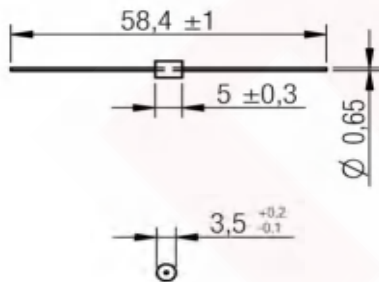
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I <sub>R</sub> 40°C max (A)	直流电阻 DCResistance DCRmax (mΩ)	电感 Inductance L <sub>p</sub> typ (μH)	固化温度 Curie Temperature T <sub>c</sub> °C
FBSC6303-82	@10MHz 32 @100MHz 82	3.00	5.00	0.460	140



### 尺寸

Dimension (mm)



### 示意图

Schematics



### 电性特性

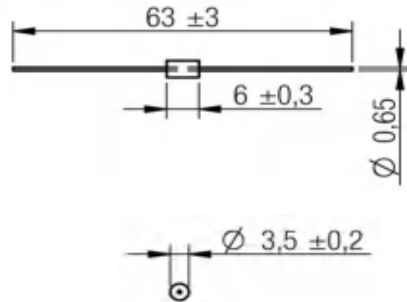
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I <sub>R</sub> 40°C max (A)	直流电阻 DCResistance DCRmax (mΩ)	电感 Inductance L <sub>p</sub> typ (μH)	固化温度 Curie Temperature T <sub>c</sub> °C
FBSC5803-83	@10MHz 49 @100MHz 83	6.00	5.00	0.737	140



### 尺寸

Dimension (mm)



### 示意图

Schematics



### 电性特性

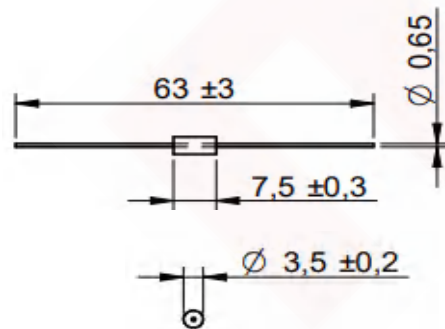
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I <sub>R</sub> 40°C max (A)	直流电阻 DCResistance DCRmax (mΩ)	电感 Inductance L <sub>p</sub> typ (μH)	固化温度 Curie Temperature T <sub>c</sub> °C
FBSC6303-89	@10MHz 35 @100MHz 89	3.00	5.00	0.550	140



### 尺寸

Dimension (mm)



### 示意图

Schematics



### 电性特性

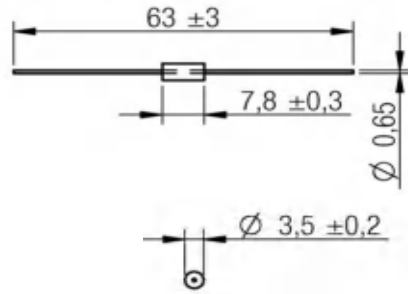
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I <sub>R</sub> 40°C max (A)	直流电阻 DCResistance DCRmax (mΩ)	电感 Inductance L <sub>p</sub> typ (μH)	固化温度 Curie Temperature T <sub>c</sub> °C
FBSC6303-100	@10MHz 50 @100MHz 100	3.00	5.00	0.633	140



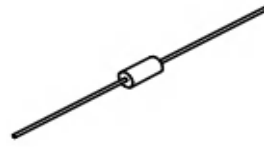
### 尺寸

Dimension (mm)



### 示意图

Schematics



### 电性特性

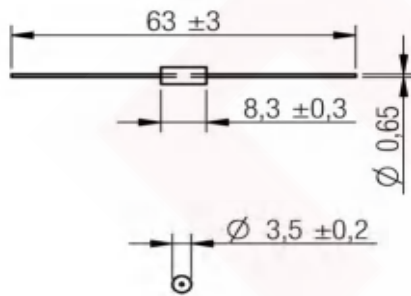
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I <sub>R</sub> 40°C max (A)	直流电阻 DCResistance DCRmax (mΩ)	电感 Inductance L <sub>p</sub> typ (μH)	固化温度 Curie Temperature T <sub>c</sub> °C
FBSC6303-100A	@10MHz 43 @100MHz 100	3.00	5.00	0.510	140



### 尺寸

Dimension (mm)



### 示意图

Schematics



### 电性特性

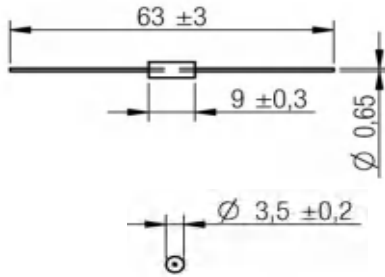
Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I <sub>R</sub> 40°C max (A)	直流电阻 DCResistance DCRmax (mΩ)	电感 Inductance L <sub>p</sub> typ (μH)	固化温度 Curie Temperature T <sub>c</sub> °C
FBSC6303-130	@10MHz 45 @100MHz 130	3.00	5.00	0.680	140



### 尺寸

Dimension (mm)



### 示意图

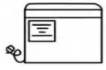
Schematics



### 电性特性

Electrical Properties

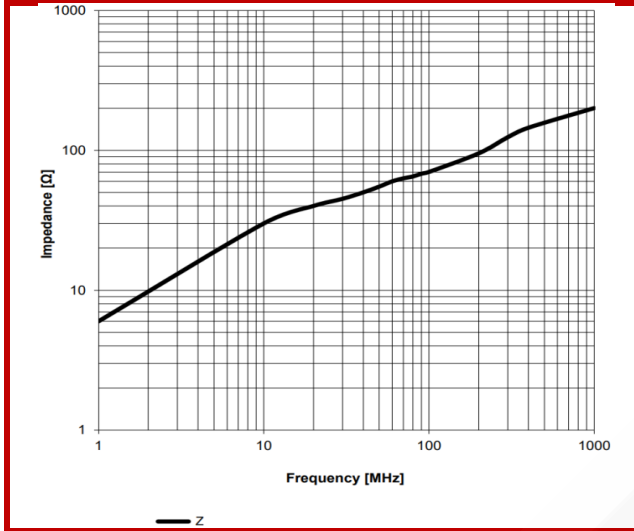
型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current I <sub>R</sub> 40°C max (A)	直流电阻 DC Resistance DCR <sub>max</sub> (mΩ)	电感 Inductance L <sub>p</sub> typ (μH)	固化温度 Curie Temperature T <sub>c</sub> °C
FBSC6303-130A	@10MHz 65 @100MHz 130	3.00	5.00	0.595	140



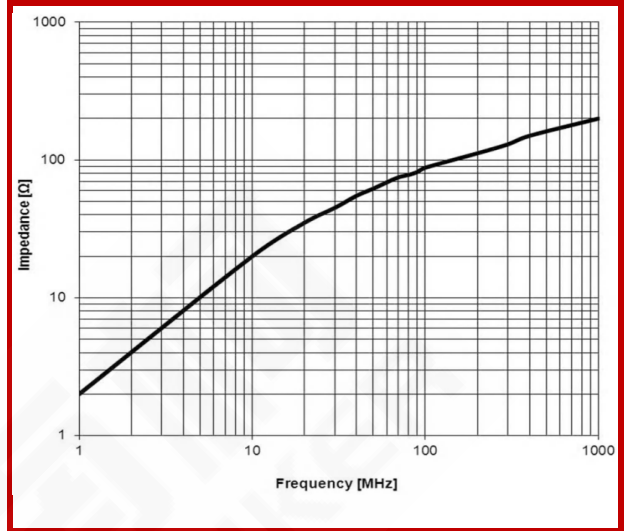
### 典型阻抗特性

Typical Impedance Characteristics

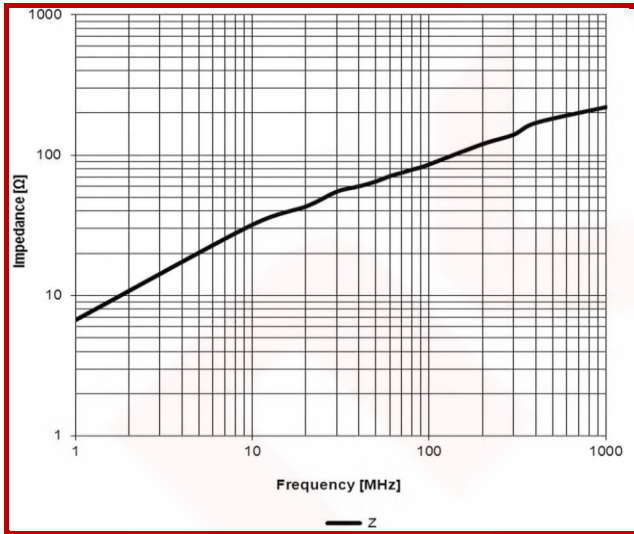
#### FBSC6303-70



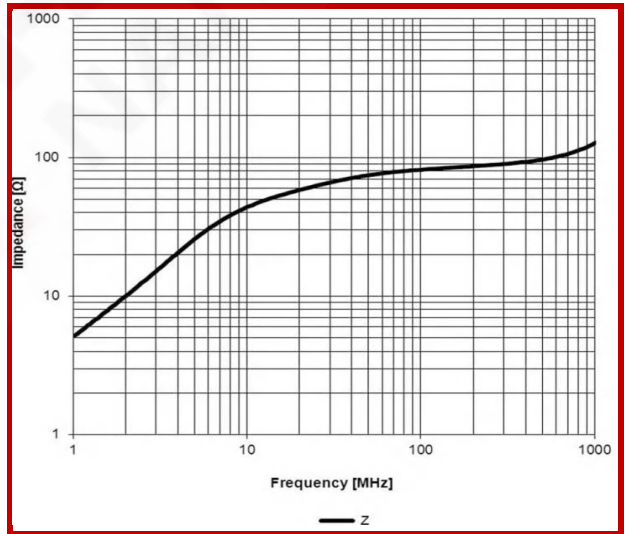
#### FBSC6303-80



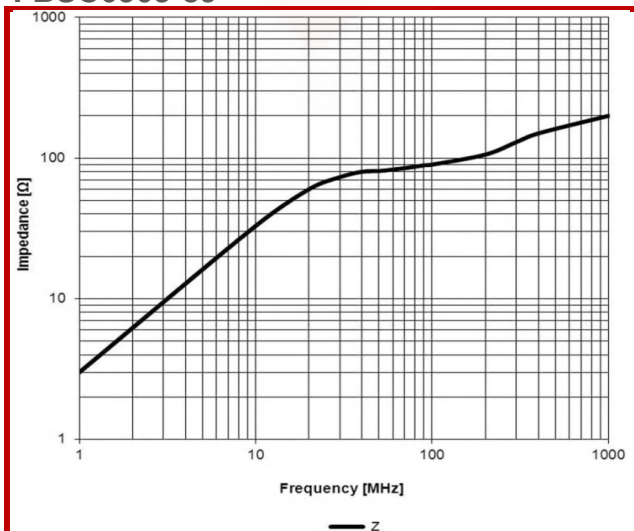
#### FBSC6303-82



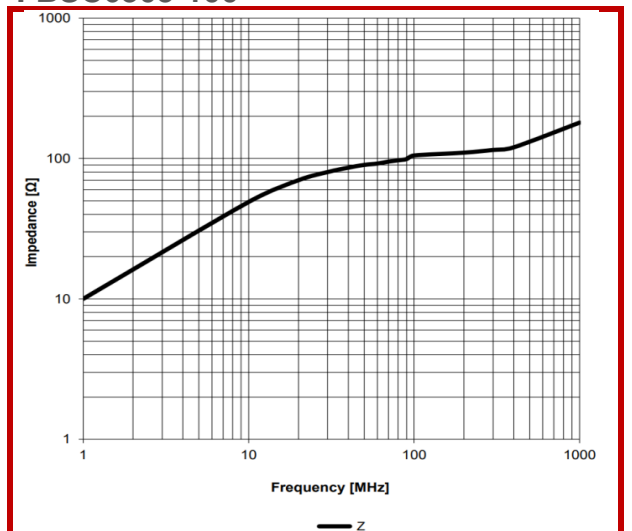
#### FBSC5803-83



#### FBSC6303-89



#### FBSC6303-100

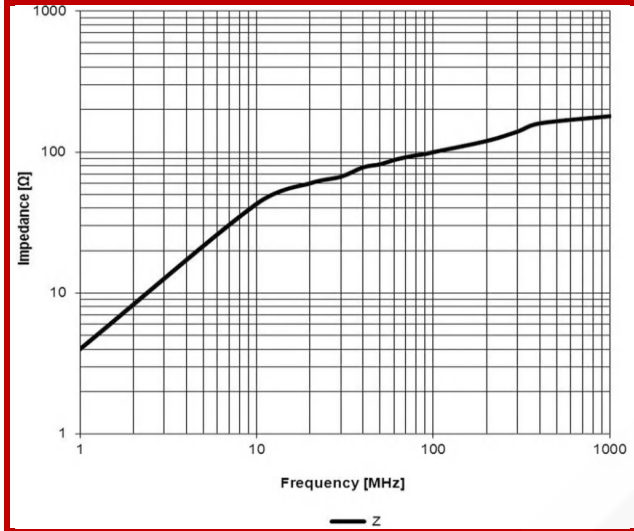




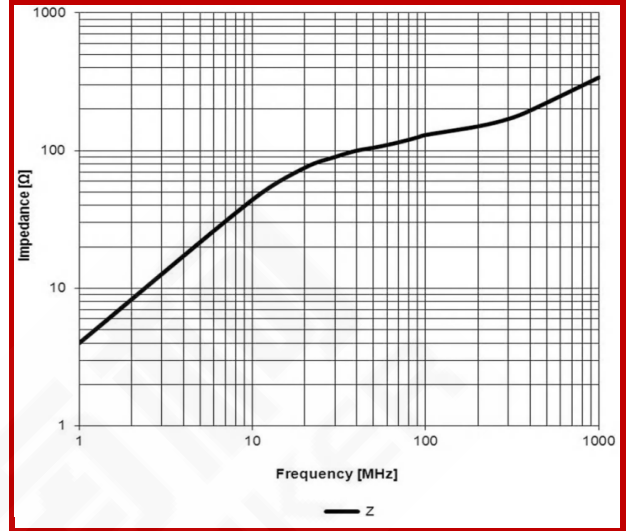
### 典型阻抗特性

Typical Impedance Characteristics

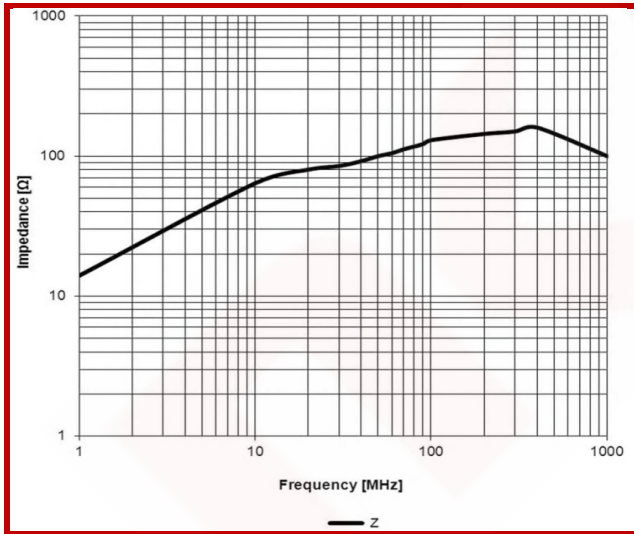
#### FBSC6303-100A

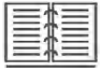


#### FBSC6303-130



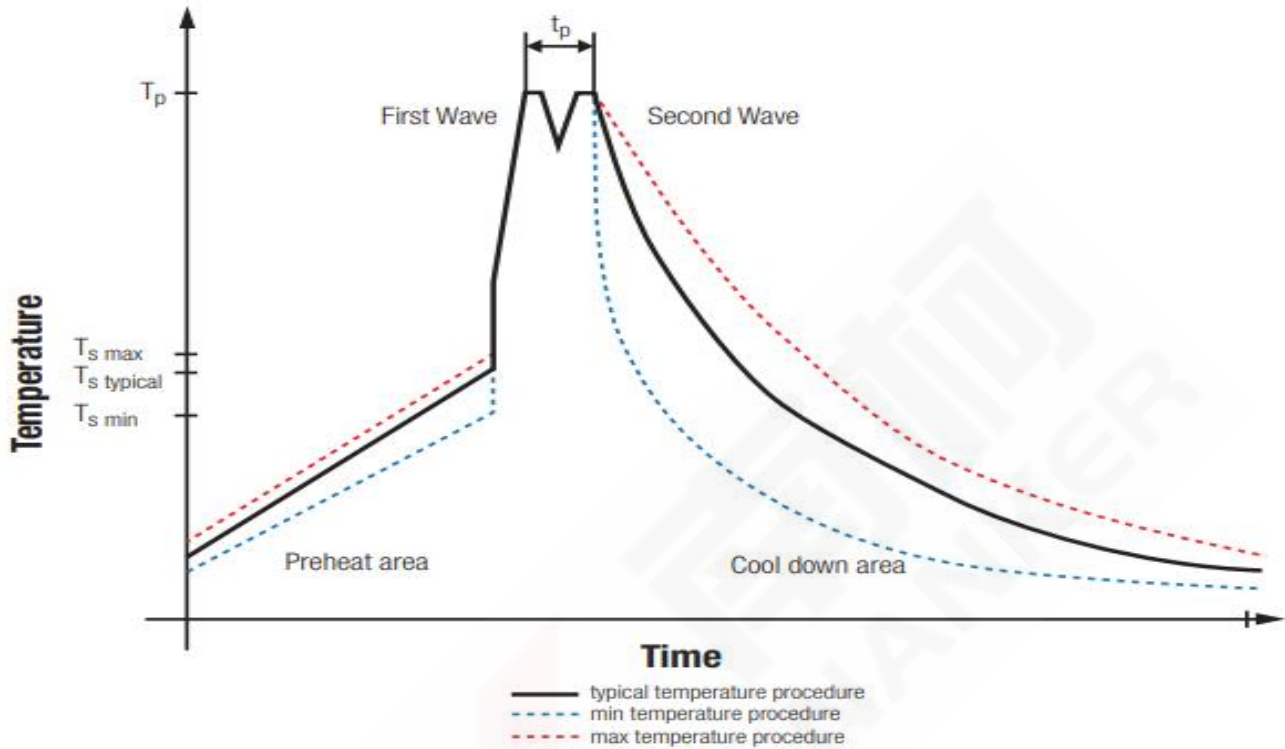
#### FBSC6303-100A





### 波峰焊线图

Classification Wave Soldering Profile



### 封装体峰值温度( $T_p$ )分类

Classification Reflow Soldering Profile:

Profile Feature			Pb-Free Assembly	Sn-Pb Assembly
Preheat Temperature Min	$T_{s \text{ min}}$	$T_{s \text{ min}}$	100°C	100°C
Preheat Temperature Typical	$T_{s \text{ typical}}$	$T_{s \text{ typical}}$	120°C	120°C
Preheat Temperature Max	$T_{s \text{ max}}$	$T_{s \text{ max}}$	130°C	130°C
Preheat Time $t_s$ from $T_{s \text{ min}}$ to $T_{s \text{ max}}$	$t_s$	$t_s$	70 seconds	70 seconds
Ramp-up Rate	$\Delta T$	$\Delta T$	150°C max	150°C max
Peak Temperature	$T_p$	$T_p$	250°C ~ 260°C	235°C ~ 260°C
Time of actual peak temperature	$t_p$	$t_p$	max. 10 seconds max. 5 seconds each wave	max. 10 seconds max. 5 seconds each wave
Ramp-down Rate, Min			~ 2K/seconds	~ 2K/seconds
Ramp-down Rate, Typical			~3.5K/seconds	~3.5K/seconds
Ramp-down Rate, Max			5K/seconds	5K/seconds
Time 25°C to 25°C			4 minutes	4 minutes

\* 波峰焊参照标准EN61760-1:2006。

Wave Soldering is refer to standard EN61760-1:2006